

TECHNICAL REPORT

IEC TR 62258-3

First edition
2005-06

Semiconductor die products –

Part 3: Recommendations for good practice in handling, packing and storage

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International Electrotechnical Commission, 3, rue de Varembé, PO Box 131, CH-1211 Geneva 20, Switzerland
Telephone: +41 22 919 02 11 Telefax: +41 22 919 03 00 E-mail: inmail@iec.ch Web: www.iec.ch



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CONTENTS

FOREWORD.....	4
INTRODUCTION.....	6
1 Scope and object.....	7
2 Normative references	7
3 Terms and definitions	8
4 Handling – Good practice	8
4.1 General	8
4.2 Working environmental controls.....	8
4.3 General handling precautions.....	8
4.4 Cleanroom good practice.....	8
5 Process handling issues	12
5.1 Wafer sawing	12
5.2 Die sorting.....	13
6 Die and wafer transport and storage media	16
6.1 Wafer carriers and cassettes.....	16
6.2 In-process carriers and transport systems.....	17
6.3 Packing for shipment of unsawn wafers.....	17
6.4 Packing for shipment of sawn wafers.....	18
6.5 Packing for shipment of single wafers	21
6.6 Packing for shipment of die using trays	21
6.7 Packing for shipment of die using tape-and-reel	25
6.8 Secondary packing for shipment	27
7 Storage good practice.....	28
7.1 Die and wafer storage	28
7.2 Short-term storage environment and conditions.....	28
7.3 Storage time limitations	28
7.4 Sawn wafer on wafer frame or ring	29
7.5 Die products in the production area	29
7.6 Die in tape-and-reel.....	29
7.7 Dry-packed die products.....	29
8 Traceability good practice.....	29
8.1 General	29
8.2 Wafer traceability	29
8.3 Die products traceability	29
8.4 Wafer and die back side marking.....	30
9 Guidelines for long-term storage (die banking) of bare die and wafers.....	30
9.1 General	30
9.2 Preparing for storage.....	30
9.3 Damage to die products during long-term storage	31
9.4 Long-term storage environment.....	31
9.5 Recommended inert atmosphere purity	32
9.6 Chemical contamination	32
9.7 Electrical effects.....	33

9.8	Protection from radiation.....	33
9.9	Periodic qualification of stored die products	33
10	Good practice for automated handling during assembly	34
10.1	Removal of die from shipping media.....	34
10.2	Equipment out of service	34
Annex A (informative) Planning checklist.....		35
Annex B (informative) Material specifications.....		41
Bibliography		44
Figure 1 – Bevel cut for bare die and flip-chip products.....		12
Figure 2 – Die eject needle		15
Figure 3 – Wafer jar structure.....		18
Figure 4 – Film frame.....		19
Figure 5 – Grip ring.....		20
Figure 6 – Single waffle pack		22
Figure 7 – Stacked waffle packs.....		23
Figure 8 – Vacuum-release trays.....		24
Figure 9 – Corner relief in the cavity of a chip tray.....		25
Figure 10 – Tape-and-reel packing structure		27
Figure 11 – Packaging material for shipment.....		27
Table 1 – Example die eject marks.....		15
Table A.1 – Planning checklist.....		35

INTERNATIONAL ELECTROTECHNICAL COMMISSION

SEMICONDUCTOR DIE PRODUCTS –

**Part 3: Recommendations for good practice
in handling, packing and storage**

FOREWORD

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The main task of IEC technical committees is to prepare International Standards. However, a technical committee may propose the publication of a technical report when it has collected data of a different kind from that which is normally published as an International Standard, for example "state of the art".

IEC 62258-3, which is a technical report, has been prepared by IEC technical committee 47: Semiconductor devices.

The text of this technical report is based on the following documents:

Enquiry draft	Report on voting
47/1794/DTR	47/1806/RVC

Full information on the voting for the approval of this technical report can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

IEC 62258, as currently conceived, consists of the following parts, under the general title *Semiconductor die products*¹

- Part 1: Requirements for procurement and use
- Part 2: Exchange data formats
- Part 3: Recommendations for good practice in handling, packing and storage
- Part 4: Questionnaire for die users and suppliers
- Part 5: Requirements for information concerning electrical simulations
- Part 6: Requirements for information concerning thermal simulations

Further parts may be added as required.

The committee has decided that the contents of this publication will remain unchanged until the maintenance result date indicated on the IEC web site under "<http://webstore.iec.ch>" in the data related to the specific publication. At this date, the publication will be

- reconfirmed;
- withdrawn;
- replaced by a revised edition, or
- amended.

A bilingual version of this publication may be issued at a later date.

¹ At the time of writing, IEC 62258-3 is the only part in existence. Other parts are under consideration.

INTRODUCTION

Organizations that helped prepare this technical report included the ESPRIT GOOD-DIE project, DPC, and JEITA.

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SEMICONDUCTOR DIE PRODUCTS –

Part 3: Recommendations for good practice in handling, packing and storage

1 Scope and object

This technical report has been developed to facilitate the production, supply and use of semiconductor die products, including:

- wafers,
- singulated bare die,
- die and wafers with attached connection structures, and
- minimally or partially encapsulated die and wafers.

This report contains suggested good practice for the handling, packing and storage of die products.

Success in manufacture of electronic assemblies containing die products is enhanced by attention to handling, storage and environmental conditions. This report provides guidelines taken from industry experience and is especially useful to those integrating die products into assemblies for the first time. It is also intended as an aid to setting up and auditing facilities that handle or use bare die products, from wafer fabrication to final assembly.

2 Normative references

The following referenced documents are indispensable for the application of this document. For dated references, only the edition cited applies. For undated references the latest edition of the referenced document (including any amendments) applies.

IEC 60050 (all parts), *International Electrotechnical Vocabulary*

IEC 60286-3, *Packaging of components for automatic handling – Part 3: Packaging of surface mount components on continuous tapes*

IEC 61340-5-1:1998, *Electrostatics – Part 5-1: Protection of electronic devices from electrostatic phenomena – General requirements*

IEC 61340-5-2:1999, *Electrostatics – Part 5-2: Protection of electronic devices from electrostatic phenomena – User guide*

IEC 62258-1, *Semiconductor die products – Part 1: Requirements for procurement and use*²

ISO 14644-1, *Cleanrooms and associated controlled environments – Part 1: Classification of air cleanliness*

² Under consideration.

3 Terms and definitions

For the purposes of this document, relevant terms which are defined in IEC 60050, together with additional terms and acronyms as given in IEC 62258-1, shall apply.

4 Handling – Good practice

4.1 General

Contact with the exposed active surface of die products should be avoided. When contact is absolutely necessary, only properly designed tools and materials should be used.

The working environment, including tools, materials and containers for handling and transport of die products should provide for ESD protection (refer to IEC 61340-5-1 and IEC 61340-5-2).

It should also be realised that die products are sensitive to certain chemicals.

4.2 Working environmental controls

The following are the typical recommended working environmental conditions for most semiconductor technologies. Characterisation of the particular technology used should be conducted to determine any specific environmental needs. This working environment should not be used for storage of semiconductor die.

- a) Temperature: 17 °C – 28 °C
- b) Humidity: 40 % nominal $\begin{matrix} +20 \\ -10 \end{matrix}$ %
- c) Particle count: ISO 14644-1, Class 8 or better

4.3 General handling precautions

The selection of appropriate tools is critical to successful handling of bare die and wafers. There is a range of specialized tools available for correct handling of die and wafers. If any tooling or equipment is found to damage die products, its use should be suspended immediately.

Die products should never be allowed to come into contact with each other, or to be stacked on top of each other without the use of suitable separators.

Die products should never be placed with the active side touching a hard surface. The die surface may also be damaged if it touches a soft surface that has embedded hard particles, such as silicon debris.

When handling wafers it is recommended that physical contact should be made only with the outer periphery and/or the back side of the wafer.

4.4 Cleanroom good practice

Containers of bare die or wafers should only be opened in a work area with a controlled environment, known as a cleanroom. This applies to any process that exposes the die or wafer surface to the environment, for example quality checks, die sorting or assembly of products containing bare die.

Personnel working in these areas need to be adequately trained to ensure that die products are not physically damaged nor contaminated when handled in the cleanroom.

4.4.1 General

ESD damage may be reduced through the use of grounded workstations, conductive wrist straps and/or shoe straps, conductive material totes, staticide chemicals, conductive floor waxes, tiles, mats, ionizers, conductive packing foams, and shielded bags. These items can also improve the efficiency of the environmental controls employed.

Bare die or wafers in process should remain in a clean environment at all times. If wafers are to be transported between cleanrooms, a suitable wafer carrier should be used and the container should remain closed during transportation. The container should be externally cleaned on re-entering the cleanroom.

It is recommended that die or wafers should not be handled manually. Handling die or wafers with bare hands should be avoided since this will cause contamination from skin oil, skin flakes, and a variety of other contaminants from human and other sources. Even when using gloves, handling may cause contamination by transfer of plasticizer from the glove. However, it is acceptable to handle wafers with a gloved hand as long as the wafer is held on the edge and the active surface is not touched at all.

All surfaces coming in contact with die products throughout the process should be clean and, when practicable, non-metallic. Any hard material in contact with the die products may cause scratches or chipping. These principles should be observed at all times, since if one die or wafer becomes contaminated, the contaminants may be transferred to other surfaces, process equipment and wafers.

Care should be taken to avoid contaminating surfaces used for product handling. Working surfaces should not be used to hold non-clean items, such as equipment covers, internal parts or personal belongings. Wiping a surface clean may not adequately remove oils and residues.

4.4.2 Attire

4.4.2.1 Hats, hoods, nets, masks and shoes

Head and facial hair should be completely enclosed at all times using appropriate hoods or nets to avoid contamination from skin particles or hair.

It is recommended that masks are worn at all times while in the production area with exposed wafers or die to prevent contamination by spittle. Masks should cover the mouth, and ideally, the nose and should be replaced daily or more often if they become contaminated.

Special ESD-safe cleanroom shoes should be worn within the cleanroom. These shoes should be kept inside the cleanroom or changing area and only be taken outside the area for cleaning or repair. Alternatively, overshoes may be used which should be discarded immediately after use in suitable waste containers. Some overshoes are suitable for re-use after washing, however, they are not intended to be re-used without being cleaned.

4.4.2.2 Smocks and gowns

Special smocks and gowns should be worn within the cleanroom, to cover normal clothing. They should be selected according to the cleanroom classification and should be made of material that is both anti-static and lint-free.

4.4.2.3 Gloves

Gloves serve as the final barrier in preventing release of skin flakes, skin oils, and other hand-carried contaminants. Disposable vinyl gloves that are approved for cleanrooms are appropriate for general use.

Cotton gloves or other gloves that shed lint or powder should not be worn in handling die products, even under vinyl gloves. Polyester or nylon gloves may be worn under vinyl gloves. Rubber gloves packed with powder should not be used.

Gloves should be replaced each time the cleanroom is entered, or more often if they become contaminated in any way, for example by ink or from touching the face. Gloves that have rips or tears should be replaced immediately.

When gowning, gloves should always be put on last, after other items. Gloves should be worn over cuffs on sleeves and should be held at the wrists only at all times.

No contact should be made with face, hair, or other potential sources of contamination by gloved hands; such contamination can be transferred to other items, including die products, process equipment and handling equipment.

4.4.2.4 Finger cots

Finger cots are often used instead of gloves. These offer less protection from contamination, but are more convenient for some operations, for example wafer quality control inspection. It is recommended that finger cots be worn on all fingers to prevent inadvertent contamination from an uncovered finger. Finger cots should be kept and used in the cleanroom area and not kept in the cleanroom gowning area.

Finger cots should not be re-used and should be replaced if torn or damaged. Fresh finger cots should be used after re-entering the cleanroom.

4.4.3 Conduct

Food and drink should not be taken into the cleanroom.

Hands should be washed before gowning and entering the work area, especially after handling foods.

Cosmetics should not be worn in the cleanroom as the chemicals they contain could damage or contaminate die products. Excessive use of creams and lotions should also be avoided since chemical additives may also damage or contaminate die products.

The following are some of the practices and items that should be prohibited in the controlled environment:

- a) smoking or the use of any tobacco product;
- b) acts of personal hygiene or grooming;
- c) hair brushes or combs;
- d) chewing-gum, sweets or candy;
- e) plants or cut flowers;
- f) pencils or erasers;
- g) paper or card products not designed for cleanroom use.

4.4.4 Tools

The use of automated equipment and vacuum tools is preferred at all times for handling die and wafers. Any tool used should not generate ESD hazards.

Tools should only be used for their designed purpose in handling die products and should not be used as screwdrivers, pry bars, letter openers, etc.